

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|---|------------------|
| - | 926 | 257/685 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 2074 | 257/686 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 4631 | 257/666 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 13:24 |
| - | 2235 | 257/690 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 2469 | 257/692 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 1660 | 257/701 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 4044 | 257/787 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:17 |
| - | 13245 | 257/685 257/686 257/666 257/690 257/692 257/701 257/787 | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:18 |
| - | 3253 | ((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 12:19 |
| - | 965 | ((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 11:22 |
| - | 27 | ((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and (lead near recess\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 13:22 |
| - | 26 | 257/666 and (lead near recess\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 13:22 |
| - | 9 | (257/666 and (lead near recess\$3)) not (((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and (lead near recess\$3)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 13:22 |
| - | 1450 | 257/666 and chip and (encapsulant encapsulating encapsulate mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 15:04 |
| - | 1019 | (257/666 and chip and (encapsulant encapsulating encapsulate mold)) not (((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 15:04 |

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| - | 781 | ((257/666 and chip and (encapsulant encapsulating encapsulate mold)) not ((257/685 257/686 257/666 257/690 257/692 257/701 257/787) and lead and (chip die IC (integrated near circuit)) and (encapsulant encapsulating encapsulate mold)) and ((I/O bond input/output) near pad))) and pad | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/22 15:05 |
| - | 294 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:26 |
| - | 1872 | lead and chip and ((I/O input/output) near pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 13:38 |
| - | 668 | (lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:28 |
| - | 505 | ((lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls.) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 13:39 |
| - | 294 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:28 |
| - | 1346 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:28 |
| - | 1052 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:28 |
| - | 516 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))) and 257/\$6.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:29 |
| - | 516 | ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output bond) near pad)) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))) and 257/\$6.ccls.) not ((lead and chip and ((I/O input/output) near pad)) and 257/\$6.ccls.) not ((metal conductive conducting conductor) near lead) and chip and ((I/O input/output) near pad))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/05 15:29 |